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CONFIRMATION NO. 7910

Bib Data Sheet

<b>SERIAL NUMBER</b> 10/500,119	<b>FILING OR 371(c) DATE</b> 06/17/2005 <b>RULE</b>	<b>CLASS</b> 174	<b>GROUP ART UNIT</b> 2841	<b>ATTORNEY DOCKET NO.</b> 1204.43988X00	
<b>APPLICANTS</b> Hidehiro Nakamura, Tsukuba-shi, JAPAN; Akishi Nakaso, Oyama-shi, JAPAN; Shigeharu Arike, Shimodate-shi, JAPAN; Fumio Inoue, Tsukuba-shi, JAPAN; Tetsuya Enomoto, Tsukuba-shi, JAPAN; Norio Moriike, Shimodate-shi, JAPAN; Kousuke Hiroki, Tsukuba-shi, JAPAN;					
<b>** CONTINUING DATA *****</b> This application is a 371 of PCT/JP02/13434 12/24/2002					
<b>** FOREIGN APPLICATIONS *****</b> JAPAN 2001-391799 12/25/2001 JAPAN 2002-126594 04/26/2002 JAPAN 2002-230095 08/07/2002					
Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met Allowance Verified and Acknowledged <u>Examiner's Signature</u> <u>Initials</u>		<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWING</b> 8	<b>TOTAL CLAIMS</b> 39	<b>INDEPENDENT CLAIMS</b> 2
<b>ADDRESS</b> 020457					
<b>TITLE</b> Connection substrate, multi-layer wiring board using the connection substrate, substrate for semiconductor package, and methods for manufacturing them					
<b>FILING FEE RECEIVED</b> 2492	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		